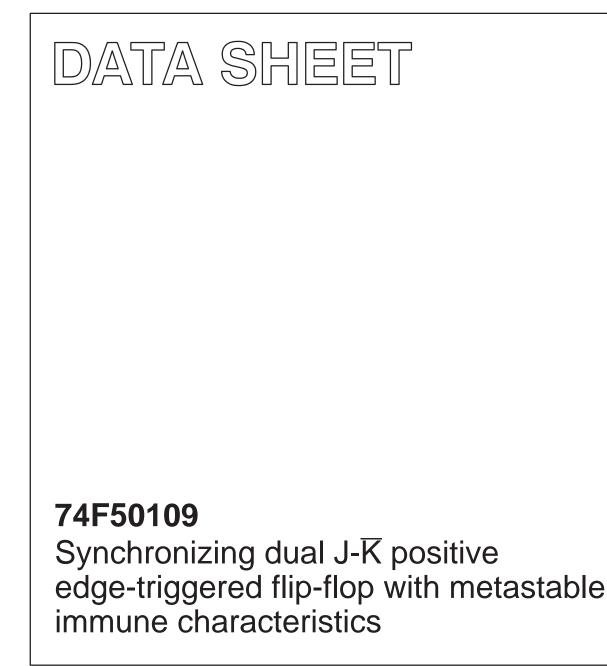
INTEGRATED CIRCUITS



Product specification

1990 Sep 14

IC15 Data Handbook



74F50109

FEATURE

- Metastable immune characteristics
- Output skew guaranteed less than 1.5ns
- High source current (I_{OH} = 15mA) ideal for clock driver applications
- Pinout compatible with 74F109
- See 74F5074 for synchronizing dual D-type flip-flop
- See 74F50728 for synchronizing cascaded D-type flip-flop
- See 74F50729 for synchronizing dual D-type flip-flop with edge-triggered set and reset

TYPE	TYPICAL f _{max}	TYPICAL SUPPLY CURRENT(TOTAL)
74F50109	150MHz	22mA

ORDERING INFORMATION

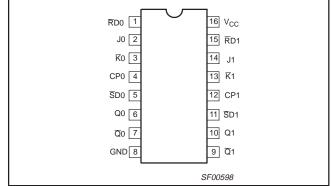
	ORDER CODE	
DESCRIPTION	$\label{eq:commercial range} \begin{array}{l} \mbox{COMMERCIAL RANGE} \\ \mbox{V}_{CC} = 5V \pm 10\%, \\ \mbox{T}_{amb} = 0^{\circ} \mbox{C to } + 70^{\circ} \mbox{C} \end{array}$	PKG DWG #
16-pin plastic DIP	N74F50109N	SOT38-4
16-pin plastic SO	N74F50109D	SOT109-1

INPUT AND OUTPUT LOADING AND FAN OUT TABLE

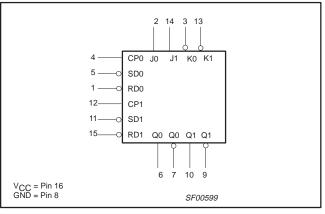
PINS	DESCRIPTION	74F (U.L.) HIGH/ LOW	LOAD VALUE HIGH/LOW
J0, J1	J inputs	1.0/0.417	20μΑ/250μΑ
K0, K1	K inputs	1.0/0.417	20μΑ/250μΑ
CP0, CP1	Clock inputs (active rising edge)	1.0/0.033	20μΑ/20μΑ
<u>S</u> D0, <u>S</u> D1	Set inputs (active low)	1.0/0.033	20μΑ/20μΑ
RD0, RD1	Reset inputs (active low)	1.0/0.033	20μΑ/20μΑ
Q0, Q1, <u>Q</u> 0, <u>Q</u> 1	Data outputs	750/33	15mA/20mA

NOTE: One (1.0) FAST unit load is defined as: 20µA in the high state and 0.6mA in the low state.

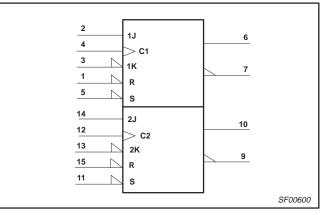




LOGIC SYMBOL

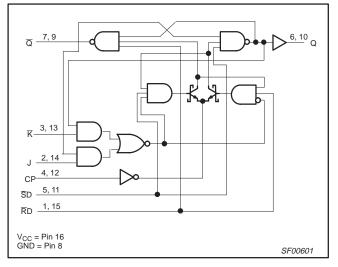


IEC/IEEE SYMBOL



74F50109

LOGIC DIAGRAM



DESCRIPTION

The 74F50109 is a dual positive edge-triggered JK-type flip-flop featuring individual J, \overline{K} , clock, set, and reset inputs; also true and complementary outputs.

Set (\overline{SD}) and reset (\overline{RD}) are asynchronous active low inputs and operate independently of the clock (CP) input.

The J and \overline{K} are edge–triggered inputs which control the state changes of the flip–flops as described in the function table. The J and \overline{K} inputs must be stable just one setup time prior to the low–to–high transition of the clock for guaranteed propagation delays. The J \overline{K} design allows operation as a D flip–flop by tying J and \overline{K} inputs together.

The 74F50109 is designed so that the outputs can never display a metastable state due to setup and hold time violations. If setup time and hold time are violated the propagation delays may be extended beyond the specifications but the outputs will not glitch or display a metastable state. Typical metastability parameters for the 74F50109 are: $\tau \cong 135 ps$ and $\tau \cong 9.8 \times 10^6$ sec where τ represents a function of the rate at which a latch in a metastable state resolves that condition and T_0 represents a function of the measurement of the propensity of a latch to enter a metastable state.

METASTABLE IMMUNE CHARACTERISTICS

Philips Semiconductors uses the term 'metastable immune' to describe characteristics of some of the products in its FAST family. Specifically the 74F50XXX family presently consist of 4 products which displays metastable immune characteristics. This term means that the outputs will not glitch or display an output anomaly under any circumstances including setup and hold time violations.

This claim is easily verified on the 74F5074. By running two independent signal generators (see Fig. 1) at nearly the same frequency (in this case 10MHz clock and 10.02 MHz data) the

device–under–test can be often be driven into a metastable state. If the Q output is then used to trigger a digital scope set to infinite persistence the \overline{Q} output will build a waveform.0 An experiment was run by continuously operating the devices in the region where metastability will occur.

When the device–under–test is a 74F74 (which was not designed with metastable immune characteristics) the waveform will appear as in Fig. 2.

Fig. 2 shows clearly that the \overline{Q} output can vary in time with respect to the Q trigger point. This also implies that the Q or \overline{Q} output waveshapes may be distorted. This can be verified on an analog scope with a charge plate CRT. Perhaps of even greater interest are the dots running along the 3.5V volt line in the upper right hand quadrant. These show that the \overline{Q} output did not change state even though the Q output glitched to at least 1.5 volts, the trigger point of the scope.

When the device–under–test is a metastable immune part, such as the 74F5074, the waveform will appear as in Fig. 3. The 74F5074 \overline{Q} output will appear as in Fig. 3. The 74F5074 Q output will not vary with respect to the Q trigger point even when the a part is driven into a metastable state. Any tendency towards internal metastability is resolved by Philips Semiconductors patented circuitry. If a metastable event occurs within the flop the only outward manifestation of the event will be an increased clock–to–Q/ \overline{Q} propagation delay. This propagation delay is, of course, a function of the metastability characteristics of the part defined by τ and T₀.

The metastability characteristics of the 74F5074 and related part types represent state–of–the–art TTL technology.

After determining the T_0 and t of the flop, calculating the mean time between failures (MTBF) is simple. Suppose a designer wants to use the 74F50729 for synchronizing asynchronous data that is arriving at 10MHz (as measured by a frequency counter), has a clock frequency of 50MHz, and has decided that he would like to sample the output of the 74F50109 10 nanoseconds after the clock edge. He simply plugs his number into the equation below:

$MTBF = e^{(t'/t)} T_o f_C f_I$

In this formula, f_C is the frequency of the clock, f_I is the average input event frequency, and t' is the time after the clock pulse that the output is sampled (t' < h, h being the normal propagation delay). In this situation the f_I will be twice the data frequency of 20 MHz because input events consist of both of low and high transitions. Multiplying f_I by f_C gives an answer of 10¹⁵ Hz². From Fig. 4 it is clear that the MTBF is greater than 10¹⁰ seconds. Using the above formula MTBF is 1.51 X 10¹⁰ seconds or about 480 years.

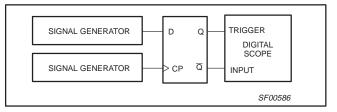
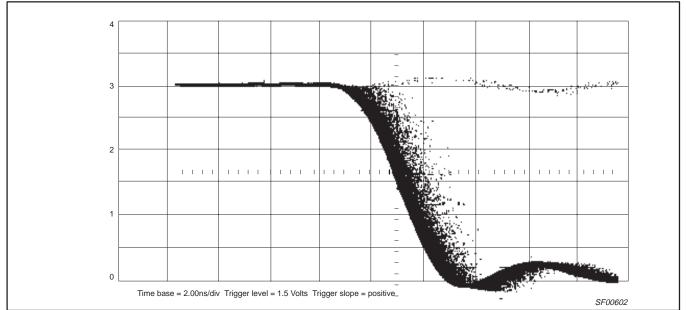


Figure 1. Test setup

74F50109



COMPARISON OF METASTABLE IMMUNE AND NON-IMMUNE CHARACTERISTICS

Figure 2. 74F74 \overline{Q} output triggered by Q output, Setup and Hold times violated

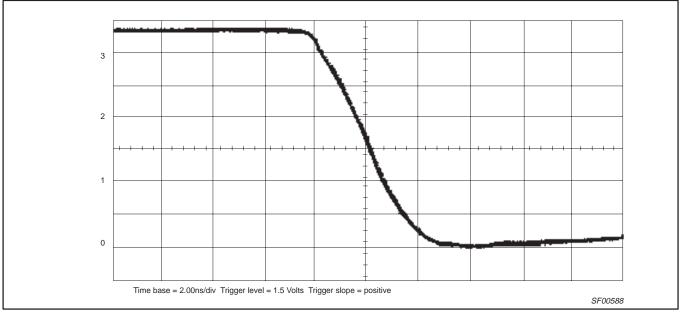
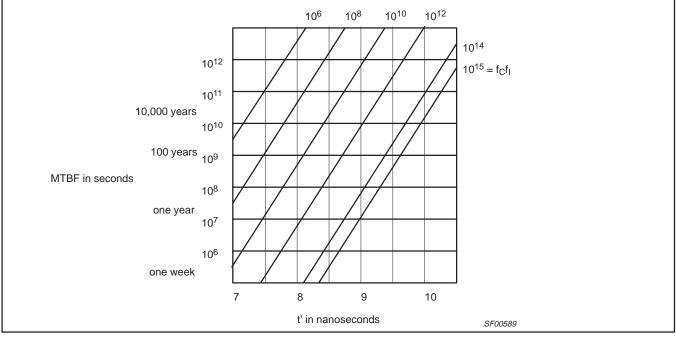


Figure 3. 74F74 $\overline{\textbf{Q}}$ output triggered by Q output, Setup and Hold times violated

74F50109

MEAN TIME BETWEEN FAILURES (MTBF) VERSUS t'



NOTE: $V_{CC} = 5V$, $T_{amb} = 25^{\circ}C$, $\tau = 135$ ps, $T_{0} = 9.8 \times 10^{8}$ sec

Figure 4.

TYPICAL VALUES FOR τ AND T_0 AT VARIOUS V_CCS AND TEMPERATURES

		T _{amb} = 0 [°] C		T _{amb} = 25°C	T _{amb} = 70 [°] C		
V _{CC}	τ Τ ₀		τ	T ₀	τ	T ₀	
5.5V	125ps	1.0 X 10 ⁹ sec	138ps	5.4 X 10 ⁶ sec	160ps	1.7 X 10 ⁵ sec	
5.0V	115ps	1.3 X 10 ¹⁰ sec	135ps	9.8 X 10 ⁶ sec	167ps	3.9 X 10 ⁴ sec	
4.5V	115ps 3.4 X 10 ¹³ sec		132ps	5.1 X 10 ⁸ sec	175ps	7.3 X 10 ⁴ sec	

FUNCTION TABLE

	11	NPUTS	3		OUTF	PUTS	OPERATING
SD	RD	СР	J	K	Q	Q	MODE
L	Н	Х	Х	Х	Н	L	Asynchronous set
Н	L	Х	Х	Х	L	Н	Asynchronous reset
L	L	Х	Х	Х	Н	Н	Undetermined*
Н	Н	1	Х	Х	q	q	Hold
Н	Н	\uparrow	h	Ι	q	q	Toggle
Н	Н	\uparrow	h	h	Н	L	Load "1" (set)
Н	Н	\uparrow	I	Ι	L	Н	Load "0" (reset)
Н	Н	\uparrow	Ι	h	q	q	Hold 'no change"

NOTES:

- H = High-voltage level
- h = High-voltage level one setup time prior to low-to-high clock transition
- = Low-voltage level L
- Low-voltage level one setup time prior to L = low-to-high clock transition
- Lower case indicate the state of the referenced q = output prior to the low-to-high clock transition
- $\begin{array}{rcl} X &= & \text{Don't care} \\ \uparrow &= & \text{Low-to-hig} \\ \uparrow &= & \text{Not low-to} \\ * &= & \text{Both output} \end{array}$ = Low-to-high clock transition
- = Not low-to-high clock transition
- Both outputs will be high if both \overline{SD} and \overline{RD} go low = simultaneously

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limit set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT			
V _{CC}	Supply voltage	-0.5 to +7.0	V			
V _{IN}	Input voltage	-0.5 to +7.0				
I _{IN}	Input current	-30 to +5	mA			
V _{OUT}	Voltage applied to output in high output state	–0.5 to V_{CC}	V			
I _{OUT}	Current applied to output in low output state	40	mA			
T _{amb}	Operating free air temperature range	0 to +70	°C			
T _{stg}	Storage temperature range	-65 to +150	°C			

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER		LIMITS		UNIT
		MIN	NOM	MAX	1
V _{CC}	Supply voltage	4.5	5.0	5.5	V
V _{IH}	High-level input voltage	2.0			V
V _{IL}	Low-level input voltage			0.8	V
I _{lk}	Input clamp current			-18	mA
I _{OH}	High-level output current			-1	mA
I _{OL}	Low-level output current			20	mA
T _{amb}	Operating free air temperature range	0		+70	°C

DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMET	ER	TE	EST			UNIT		
			COND	ITIONS ¹	-	MIN	TYP ²	MAX	
V _{OH}	High-level output voltage		$V_{CC} = MIN, V_{IL} =$	I _{OH} = MAX	±10%V _{CC}	2.5			V
			MAX, V _{IH} = MIN		±5%V _{CC}	2.7	3.4		V
V _{OL}	Low-level output voltage		V _{CC} = MIN, V _{IL} = MAX,	I _{OL} = MAX	±10%V _{CC}		0.30	0.50	V
		$V_{IH} = MIN$		±5%V _{CC}		0.30	0.50	V	
V _{IK}	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$		-0.73	-1.2	V		
lı	Input current at maximum	nput voltage	$V_{CC} = MAX, V_I = 7.0V$			100	μΑ		
I _{IH}	High-level input current		$V_{CC} = MAX, V_I = 2.7V$			20	μΑ		
IIL	Low-level input current	Jn, Kn	$V_{CC} = MAX, V_I = 0.5V$					-250	μΑ
		CPn, SDn, RDn	$V_{CC} = MAX, V_I = 0.5V$			-20	μΑ		
I _{OS}	Short circuit output current	3	$V_{CC} = MAX$	-60		-150	mA		
I _{CC}	Supply current ⁴ (total)		V _{CC} = MAX		22	32	mA		

NOTES:

1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

2. All typical values are at $V_{CC} = 5V$, $T_{amb} = 25^{\circ}C$.

3. Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

4. Measure I_{CC} with the clock input grounded and all outputs open, then with Q and \overline{Q} outputs high in turn.

AC ELECTRICAL CHARACTERISTICS

			LIMITS							
SYMBOL	PARAMETER	TEST CONDITION	V.	_{mb} = +25 _{CC} = +5.0 C _L = 50pF C _L = 500⊆	V ;	$T_{amb} = 0^{\circ}C$ $V_{CC} = +5.$ $C_{L} = 5$ $R_{L} = 5$	UNIT			
			MIN	TYP	MAX	MIN	MAX	1		
f _{max}	Maximum clock frequency	Waveform 1	130	150		90		ns		
t _{PLH} t _{PHL}	Propagation delay CPn to Qn or Qn	Waveform 1	2.0 2.0	3.8 3.8	6.0 6.0	2.0 2.0	6.5 6.5	ns		
t _{PLH} t _{PHL}	Propagation delay SDn, RDn to Qn or Qn	Waveform 2	3.5 3.5	5.5 5.5	8.0 8.0	3.0 3.0	8.5 8.5	ns		
t _{sk(o)}	Output skew ^{1, 2}	Waveform 4			1.5		1.5	ns		

NOTES:

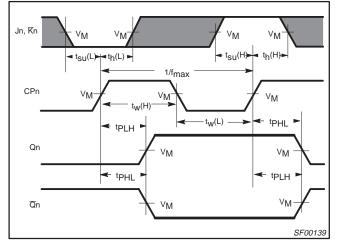
1. $|t_{PN} \text{ actual} - t_{PM} \text{ actual}|$ for any output compared to any other output where N and M are either LH or HL. 2. Skew times are valid only under same test conditions (temperature, V_{CC}, loading, etc.,).

AC SETUP REQUIREMENTS

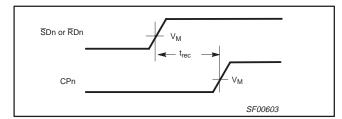
					LI	MITS		
				_{mb} = +25			C to +70°C	
SYMBOL	PARAMETER	TEST		_{CC} = +5.0			0V ± 10%	
		CONDITION	C F	; _L = 50pF R _L = 500⊆	, 2	C _L = 5 R _L = 5		
			MIN	TYP	MAX	MIN	MAX	1
t _{su} (H) t _{su} (L)	Setup time, high or low Jn, Kn to CPn	Waveform 1	1.5 1.5			2.0 2.0		ns
t _h (H) t _h (L)	Hold time, high or low Jn, Kn to CPn	Waveform 1	1.0 1.0			1.5 1.5		ns
t _w (H) t _w (L)	CPn pulse width, high or low	Waveform 1	3.0 4.0			3.5 5.0		ns
t _w (L)	SDn or RDn pulse width, low	Waveform 2	3.5			4.0		ns
t _{rec}	Recovery time SDn or RDn to CP	Waveform 3	3.0			3.5		ns

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AC WAVEFORMS



Waveform 1. Propagation delay for data to output, data setup time and hold times, and clock width, and maximum clock frequency



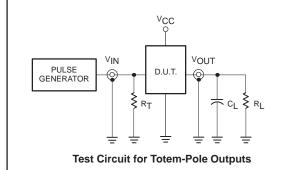
Waveform 3. Recovery time for set or reset to output

NOTES:

For all waveforms, $V_M = 1.5V$.

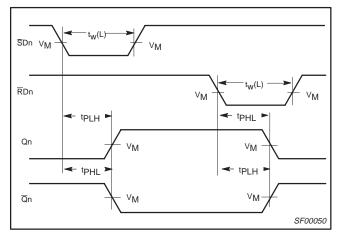
The shaded areas indicate when the input is permitted to change for predictable output performance.

TEST CIRCUIT AND WAVEFORM

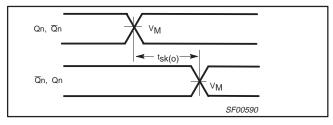


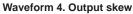
DEFINITIONS:

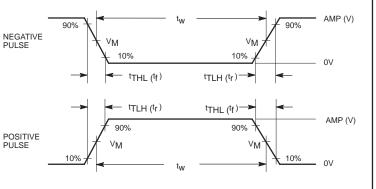
- R_L = Load resistor;
- see AC ELECTRICAL CHARACTERISTICS for value. C_L = Load capacitance includes jig and probe capacitance;
- see AC ELECTRICAL CHARACTERISTICS for value. R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.



Waveform 2. Propagation delay for set and reset to output, set and reset pulse width







Input Pulse Definition

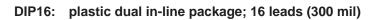
family	INP	INPUT PULSE REQUIREMENTS											
	amplitude	V _M	rep. rate	tw	t _{TLH}	t _{THL}							
74F	3.0V 1.5V		1MHz	500ns	2.5ns	2.5ns							

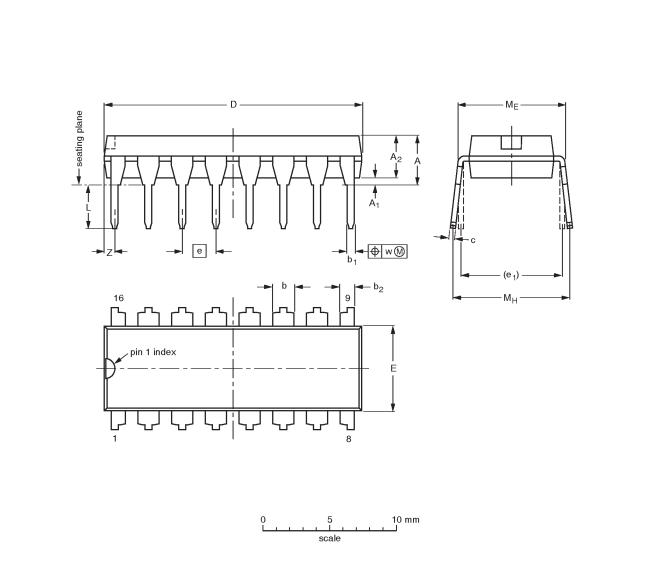
Product specification

Synchronizing dual J- \overline{K} positive edge-triggered flip-flop with metastable immune characteristics

74F50109

SOT38-4





DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	b ₂	c	d ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	1.25 0.85	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	0.76
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.049 0.033	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.030

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT38-4						-92-11-17 95-01-14

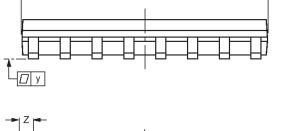
SO16:

Synchronizing dual J- \overline{K} positive edge-triggered flip-flop with metastable immune characteristics

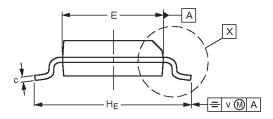
plastic small outline package; 16 leads; body width 3.9 mm

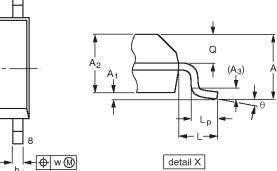
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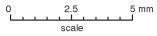
pin 1 index



D







bp

DIMENSIONS (inch dimensions are derived from the original mm dimensions)

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UNIT	A max.	A ₁	A ₂	A ₃	b _р	с	D ⁽¹⁾	E ⁽¹⁾	е	Η _E	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8 ⁰
inches	0.069	0.010 0.004	0.057 0.049	0.01		0.0100 0.0075		0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016		0.01	0.01	0.004	0.028 0.012	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	1550E DATE
SOT109-1	076E07S	MS-012AC			-95-01-23 97-05-22

74F50109

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NOTES

74F50109

Data sheet status

Data sheet status	Product status	Definition ^[1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

[1] Please consult the most recently issued datasheet before initiating or completing a design.

Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition - Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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